



SOT1893-1

CLSON12, ceramic, low-profile small outline package, no lead; 12 terminals; 0.8 mm pitch; 4 mm x 5 mm x 1.365 mm body

4 January 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	CLSON12
Package style descriptive code	CLSON (ceramic low-profile small outline; no leads)
Package body material type	C (ceramic)
Mounting method type	S (surface mount)
Issue date	19-12-2018
Manufacturer package code	98ASA01007D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	4	-	mm
package height	-	1.365	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	12	-	



CLSON12, ceramic, low-profile small outline package, no lead; 12 terminals; 0.8 mm pitch; 4 mm x 5 mm x 1.365 mm body

2 Package outline

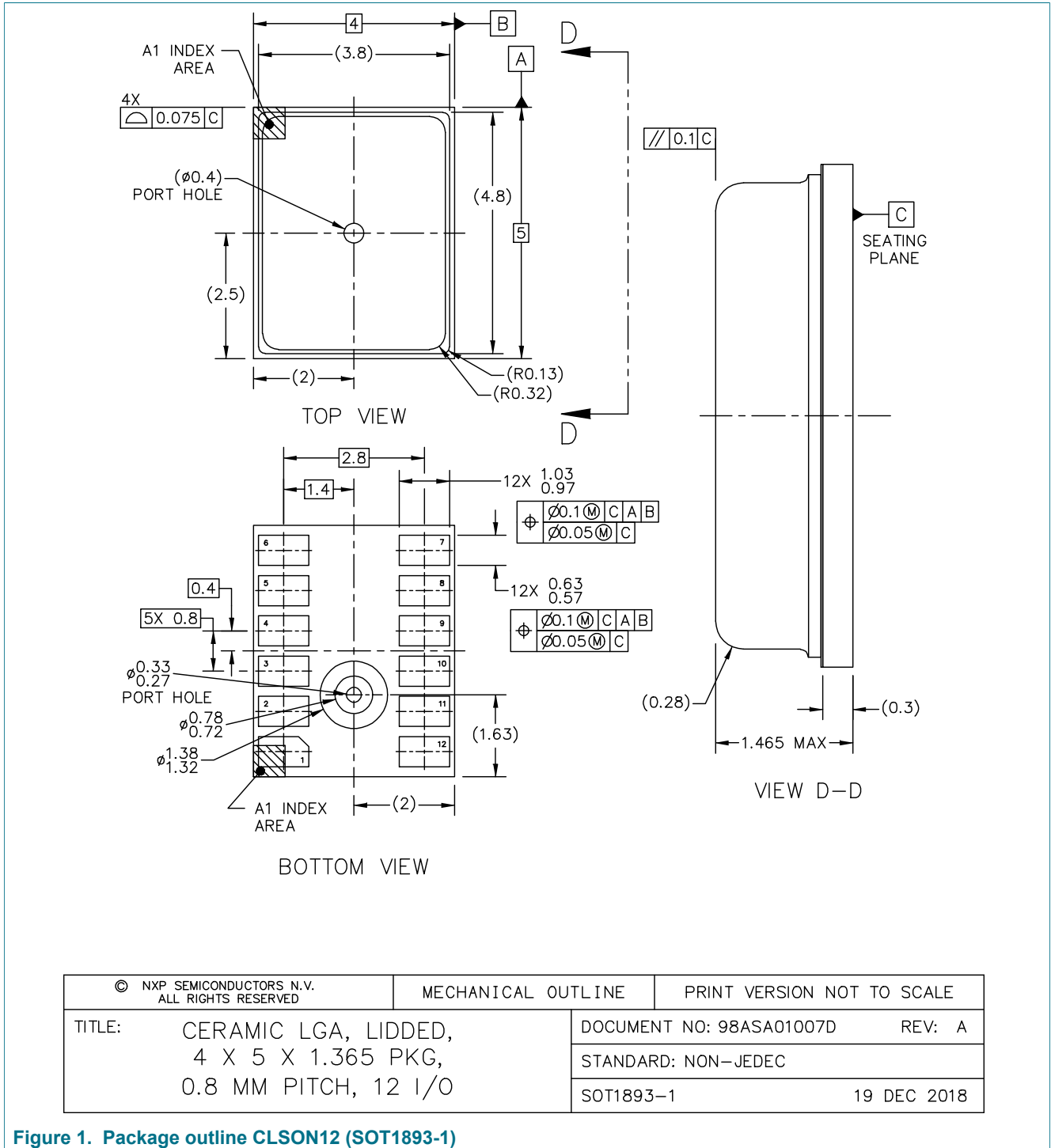


Figure 1. Package outline CLSON12 (SOT1893-1)

CLSON12, ceramic, low-profile small outline package, no lead; 12 terminals; 0.8 mm pitch; 4 mm x 5 mm x 1.365 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

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TITLE: CERAMIC LGA, LIDDED, 4 X 5 X 1.365 PKG, 0.8 MM PITCH, 12 I/O	DOCUMENT NO: 98ASA01007D	REV: A	
	STANDARD: NON-JEDEC		
	SOT1893-1	19 DEC 2018	

Figure 2. Package outline note CLSON12 (SOT1893-1)

3 Legal information

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